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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Daisuke HIROKANE

SERIAL NO.: NEW U.S. PCT APPLICATION

FILED: HEREWITH

INTERNATIONAL APPLICATION NO.: PCT/JP05/04705

INTERNATIONAL FILING DATE: March 10, 2005

FOR: EPOXY RESIN COMPOSITION FOR THE ENCAPSULATION OF
SEMICONDUCTORS AND SEMICONDUCTOR DEVICES

**REQUEST FOR PRIORITY UNDER 35 U.S.C. 119
AND THE INTERNATIONAL CONVENTION**

Commissioner for Patents
Alexandria, Virginia 22313

Sir:

In the matter of the above-identified application for patent, notice is hereby given that
the applicant claims as priority:

COUNTRY
Japan

APPLICATION NO
2004-100256

DAY/MONTH/YEAR
30 March 2004

Certified copies of the corresponding Convention application(s) were submitted to the
International Bureau in PCT Application No. PCT/JP05/04705.

Respectfully submitted,
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